

TECHNICAL DATA DATA SHEET 242, REV -

# SILICON SCHOTTKY RECTIFIER DIE Ultra Low Reverse Leakage

# **Applications:**

• Switching Power Supply • Converters • Free-Wheeling Diodes • Polarity Protection Diode

#### Features:

- Ultra low Reverse Leakage Current
- Soft Reverse Recovery at Low and High Temperature
- Very Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- High Surge Capacity
- Guard Ring for Enhanced Durability and Long Term Reliability
- Guaranteed Reverse Avalanche Characteristics
- Electrically / Mechanically Stable during and after packaging
- Out Performs 100 Volt Ultrafast Rectifiers

## **Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	$V_{RWM}$	-	100	V
Max. Average Forward Current	I <sub>F(AV)</sub>	50% duty cycle, rectangular wave form	60	Α
Max. Peak One Cycle Non- Repetitive Surge Current	I <sub>FSM</sub>	10 ms, Sine pulse (1)	720	Α
Non-Repetitive Avalanche Energy	E <sub>AS</sub>	T <sub>J</sub> = 25 °C, I <sub>AS</sub> = 1 A, L = 30mH	15	mJ
Repetitive Avalanche Current	I <sub>AR</sub>	$I_{AS}$ decay linearly to 0 in 1 μs f limited by $T_J$ max $V_A$ =1.5 $V_R$	1	Α
Max. Junction Temperature	$T_J$	-	-55 to +175	°C
Max. Storage Temperature	T <sub>stq</sub>	-	-55 to +175	°C

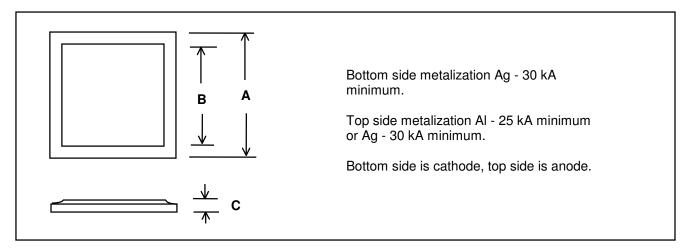
#### **Electrical Characteristics:**

Characteristics	<b>Symbol</b>	Condition	Max.	Units		
Max. Forward Voltage Drop	$V_{F1}$	@ 60A, Pulse, T <sub>J</sub> = 25 °C	0.87	V		
	$V_{F2}$	@ 60A, Pulse, T <sub>J</sub> = 125 °C	0.72	V		
Max. Reverse Current	I <sub>R1</sub>	@V <sub>R</sub> = 100V, Pulse,	30	μΑ		
		T <sub>J</sub> = 25 °C		•		
	I <sub>R2</sub>	$@V_R = 100V, Pulse,$	3.0	mA		
		T <sub>J</sub> = 125 °C				
Max. Junction Capacitance	$C_T$	$@V_R = 5V, T_C = 25  ^{\circ}C$	1500	pF		
		$f_{SIG} = 1MHz,$				
		$I_{SIG} = 50 \text{mV (p-p)}$				

(1) in SHD package

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## **Rectifier Die Outlines**



	Nominal Size	Α	В	С
Die Type	(Inches)	Inches (mm)	Inches (mm)	Inches (mm)
		+/003 (.077)	+/003 (.077)	+/001 (.026)
SCHOTTKY	.200	.200 (5.08)	.191 (4.85)	.014 (0.36)

### Metalization

A = Aluminum Top/ Silver Bottom

B = Silver Top/ Silver Bottom

C = Silver Bottom/ Aluminum Plated Molybdenum Tab Top



#### **TECHNICAL DATA**

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